



Material Content Data Sheet



Sales Product Name	TLE8088EM			Issued	1. August 2018			
MA#	MA001686794							
Package	PG-SSOP-24-9			Weight*	150.37 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.412	1.60	1.60	16042	16042
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		447	
	non noble metal	iron	7439-89-6	1.345	0.89		8945	
wire	non noble metal	copper	7440-50-8	54.617	36.32	37.26	363219	372723
	non noble metal	copper	7440-50-8	0.479	0.32	0.32	3183	3183
	encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1164
encapsulation	plastics	epoxy resin	-	8.049	5.35		53529	
	inorganic material	silicondioxide	60676-86-0	79.267	52.72	58.19	527148	581841
leadfinish	non noble metal	tin	7440-31-5	2.911	1.94	1.94	19358	19358
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1558	1558
glue	plastics	epoxy resin	-	0.199	0.13		1324	
	noble metal	silver	7440-22-4	0.597	0.40	0.53	3971	5295
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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